Product / Package Information

Package	LP4E - SiGe
Body Size	
Lead Count	
Terminal Finish	100Sn
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.81 E-02	86.20	862000	43.29	432880
Thermosets	Epoxy resin	Proprietary	1.26 E-03	6.00	60000	3.01	30131
Thermosets	Phenol Resin	Proprietary	1.26 E-03	6.00	60000	3.01	30131
Other inorganic materials	Metal Hydroxide	Proprietary	3.15 E-04	1.50	15000	0.75	7533
Other inorganic materials	Carbon Black	1333-86-4	6.30 E-05	0.30	3000	0.15	1507
Subtotal			2.10 E-02	100.00	1000000	50.22	502181

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.79 E-02	97.50	975000	42.88	428846
Copper & its alloys	Iron	7439-89-6	4.32 E-04	2.35	23500	1.03	10336
Copper & its alloys	Zinc	7440-66-6	2.21 E-05	0.12	1200	0.05	528
Copper & its alloys	Phosphorus	7723-14-0	5.52 E-06	0.03	300	0.01	132
Subtotal			1.84 E-02	100.00	1000000	43.98	439842

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.65 E-04	100.00	1000000	1.59	15908

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.33 E-04	99.99	1000000	0.80	7954

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.76 E-04	100.0	1000000	1.62	16176

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.25 E-04	70.00	700000	1.26	12557
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	1.50 E-04	20.00	200000	0.36	3588
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	5.63 E-05	7.50	75000	0.13	1345
Other organic materials	Phenolic hardener	92-88-6	1.13 E-05	1.50	15000	0.03	269
Other organic materials	Butyl cellosolve acetate	112-07-2	7.50 E-06	1.00	10000	0.02	179
Subtotal			7.50 E-04	100.0	1000000	1.79	17939

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.18 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	LP4- SiGe
Body Size	
Lead Count	
Terminal Finish	SnPb
MS Number	

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.87 E-02	87.23	872326	44.19	441930
Thermosets	Phenol Resin	Proprietary	8.32 E-04	3.89	38893	1.97	19704
Thermosets	Epoxy resin	Proprietary	1.60 E-03	7.49	74938	3.80	37965
Thermosets	Brominated Epoxy Resin	40039-93-8	1.05 E-04	0.49	4911	0.25	2488
Other inorganic materials	Antimony Trioxide	1309-64-4	1.20 E-04	0.56	5617	0.28	2846
Other inorganic materials	Carbon Black	1333-86-4	7.09 E-05	0.33	3313	0.17	1679
Subtotal			2.14 E-02	100.00	1000000	50.66	506611

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.79 E-02	97.50	975000	42.46	424566
Copper & its alloys	Iron	7439-89-6	4.32 E-04	2.35	23500	1.02	10233
Copper & its alloys	Zinc	7440-66-6	2.21 E-05	0.12	1200	0.05	523
Copper & its alloys	Phosphorus	7723-14-0	5.52 E-06	0.03	300	0.01	131
Subtotal			1.84 E-02	100.00	1000000	43.55	435453

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.70 E-04	85.0	850000	1.35	13500
Tin & its alloys	Lead	7439-92-1	1.01 E-04	15.0	150000	0.24	2382
Subtotal			6.71 E-04	100.0	1000000	1.59	15882

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.33 E-04	99.99	1000000	0.79	7875

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.94 E-04	100.0	1000000	1.64	16419

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.25 E-04	70.00	700000	1.24	12432
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	1.50 E-04	20.00	200000	0.36	3552
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	5.63 E-05	7.50	75000	0.13	1332
Other organic materials	Phenolic hardener	92-88-6	1.13 E-05	1.50	15000	0.03	266
Other organic materials	Butyl cellosolve acetate	112-07-2	7.50 E-06	1.00	10000	0.02	178
Subtotal			7.50 E-04	100.0	1000000	1.78	17760

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.22 E-02**	**100.00**	**1000000**

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